



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information	*: Required Field	

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2025-07-22
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDRF CHAMPION	Representative title	MDRFMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement
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Legal statement
Supplier acceptance* true Legal declaration* Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32U585QII6Q	23PG*482XXXU	A	9991	2025-07-22
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	80	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Tin - 3.5Ag	Not Applicable	NAC	0	
Package designator	Package size	Number of instances	Shape	
BGA	7x7	132	Bulk solder	
Comment	Package : A0G8 UFBGA 7X7X0.6 132L P 0.5 R 12X12 8298393			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015			Response
1 - Product(s) meets EU RoHS requirement without any exemptions			true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)			false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)			false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions			false
Exemption Id.	Description		

QueryList : REACH-25th June 2025				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
	#N/A			



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	23PG*482XXXU		79.729		6000000	1000000
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	14.706	mg	supplier	die	Silicon (Si)	7440-21-3		14.135	mg	961172	177288
				supplier	metallization	Aluminium (Al)	7429-90-5		0.063	mg	4284	790
				supplier	metallization	Copper (Cu)	7440-50-8		0.188	mg	12784	2358
				supplier	passivation	Nickel (Ni)	7440-02-0		0.001	mg	68	13
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.032	mg	2176	401
				supplier	metallization	Titanium (Ti)	7440-32-6		0.008	mg	544	100
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	68	13
				supplier	Passivation	Silicon Nitride	12033-89-5		0.045	mg	3060	564
				supplier	Passivation	Silicon Oxide	7631-86-9		0.233	mg	15844	2922
Substrate (A27839)	Copper & its alloys	19.579	mg	supplier	Substrate	Continuous Filament Fiber Glass	65997-17-3		2.545	mg	130000	31924
				supplier	Substrate	Bismaleimide	105391-33-1		1.077	mg	55000	13506
				supplier	Substrate	Triazine	25722-66-1		1.077	mg	55000	13506
				supplier	Substrate	Epoxy Resin	9003-36-5		2.154	mg	110000	27013
				supplier	Substrate	Inorganic filler	24623-77-6		0.979	mg	50000	12278
				supplier	Substrate	Copper (Cu)	7440-50-8		6.265	mg	320000	78582
				supplier	Substrate	Gold (Au)	7440-57-5		0.392	mg	20000	4911
				supplier	Substrate	Nickel(Ni)	7440-02-0		1.371	mg	70000	17190
				supplier	Substrate	Acrylic Resin	Proprietary		0.979	mg	50000	12278
				supplier	Substrate	Barium Sulfate	7727-43-7		0.587	mg	30000	7367
				supplier	Substrate	Silica	7631-86-9		0.392	mg	20000	4911
				supplier	Substrate	Talc containing no asbestiform fibers	14807-96-6		0.392	mg	20000	4911
				supplier	Substrate	Dipropylene Glycol Monomethyl Ether	34590-94-8		0.392	mg	20000	4911
				supplier	Substrate	3-Methoxy-3-Methyl Butyl-Acetate	Proprietary		0.392	mg	20000	4911
				supplier	Substrate	Epoxy Resin	85954-11-6		0.587	mg	30000	7367
				supplier	Glue or tape	Butadiene, acrylonitrile polymer, carboxy-terminated	68610-41-3		2.778	mg	650000	34844
				supplier	Glue or tape	Formaldehyde, polymer with (chloromethyl)oxirane	37382-79-9		1.069	mg	250000	13402
				supplier	Glue or tape	Dapsone	80-08-0		0.256	mg	60000	3216
DAF (ATB-125-12)	Precious metals	4.274	mg	supplier	Glue or tape	[3-(2,3-Epoxypropoxy)propyl]trimethoxysilane	2530-83-8		0.085	mg	20000	1072
				supplier	Glue or tape	Reaction product: bisphenol-A-(epichlorohydrin); ep	25068-38-6		0.085	mg	20000	1072
				supplier	Bonding wire	Copper (Cu)	7440-50-8		0.517	mg	965500	6479
Bonding wire (Cu)	Precious metals	0.535	mg	supplier	Bonding wire	Palladium (Pd)	7440-05-3		0.017	mg	31000	208
				supplier	Bonding wire	Gold (Au)	7440-57-5		0.002	mg	3500	23
				supplier	Molding Compound	Silica(Fused)	60676-86-0		33.683	mg	900000	422462
Encapsulation (KE-G1250AAS)	Other inorganic materials	37.425	mg	supplier	Molding Compound	Epoxy resin	Proprietary		1.984	mg	53000	24878
				supplier	Molding Compound	Phenol resin	Proprietary		1.609	mg	43000	20184
				supplier	Molding Compound	Carbon Black	1333-86-4		0.150	mg	4000	1878
Solder Balls (96.5Sn 3.5Ag)	Other Nonferrous metals & alloys	3.210	mg	supplier	Matte Sn	Tin (Sn)	7440-31-5		3.098	mg	965000	38852
				supplier	Matte Sn	Silver (Ag)	7440-22-4		0.112	mg	35000	1409